

1.0 INTRODUCTION

This drawing describes the requirements for procuring one of four unpackaged integrated circuit dice used in the manufacture of part number IH401AJE, a Quad Varafet Switch. Each individual die is a monolithic combination of a varactor diode and an N-channel junction Field Effect Transistor (JFET). All changes and/or substitutions to the procured parts are subject to prior approval by Interpoint. This specification is to be used with GEN-008.

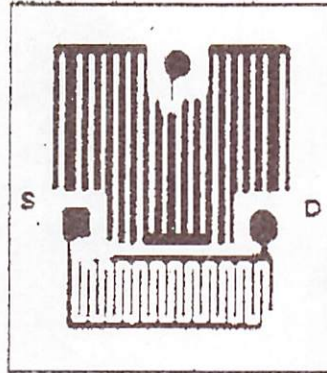
2.0 APPLICABLE DOCUMENTS

GEN-008 General Specification for Integrated Circuit Dice

3.0 REQUIREMENTS

3.1 Mechanical/Physical Characteristics

Each die shall be configured as shown in Figure 1.



NOTES:

1. Mfr. Intersil
2. Die size .025 X .022 ± .005
3. Topside Metallization: Al
4. Backside Metallization (Gate): None

FIGURE 1 - DIE CONFIGURATION

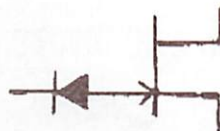


FIGURE 2 - SCHEMATIC DIAGRAM

interpoint

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SIZE A	CAGE NO. 50821	DRAWING NO. 84048	REV D
SCALE		SHEET 2 OF 3	

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